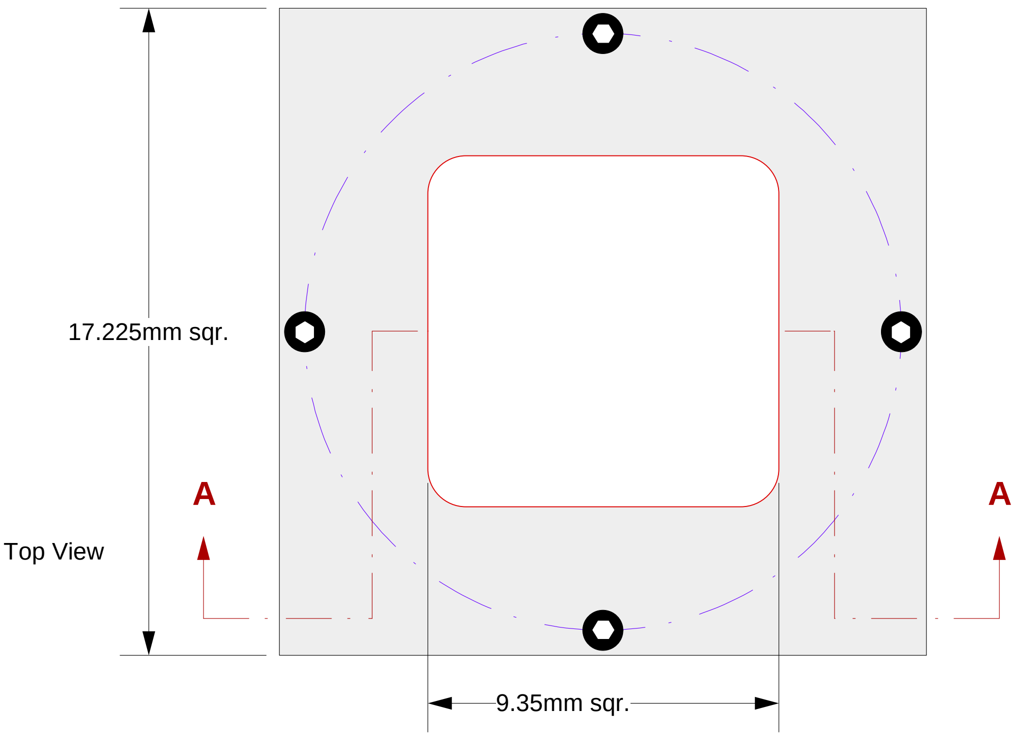
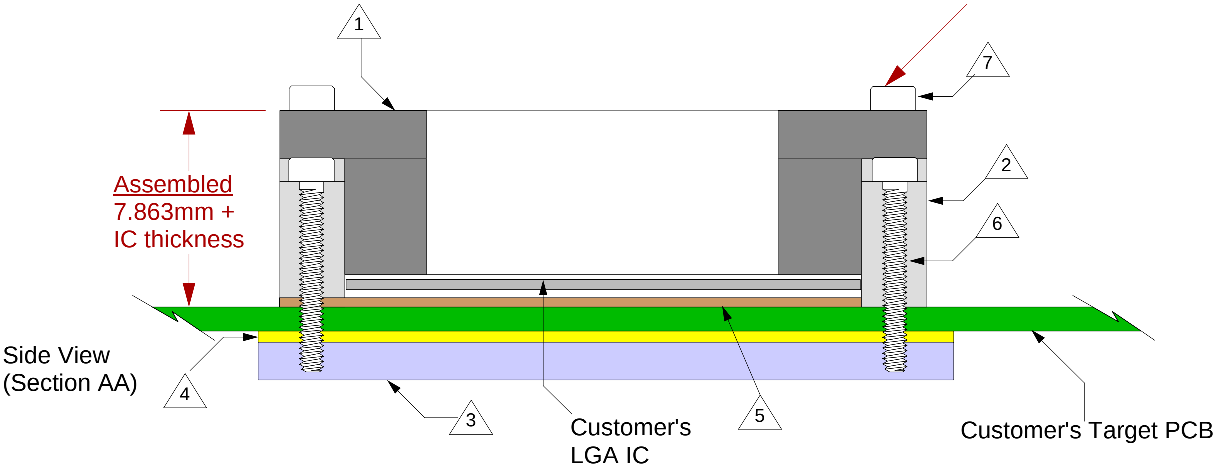
40 GHz LGA Socket - Direct mount, solderless



Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Easily removable swivel socket lid

Recommended torque per screw = 0.6-1.0 in-lb



1	Socket Lid: Black anodized Aluminum with compression plate; Thickness = 2.5mm, ~5mm projection for compression
2	Socket base: Black anodized Aluminum. Thickness = 5mm.
3	Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.
4	Insulation Plate: FR4/G10, Thickness = 1.59mm.
5	Interposer: Copper plated kapton and conductive elastomer; Thickness = 0.363mm.
6	Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread , 9.525mm long.
7	Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.

XG-LGA-7001 Drawing	Status: Released	Scale: -	Rev: B
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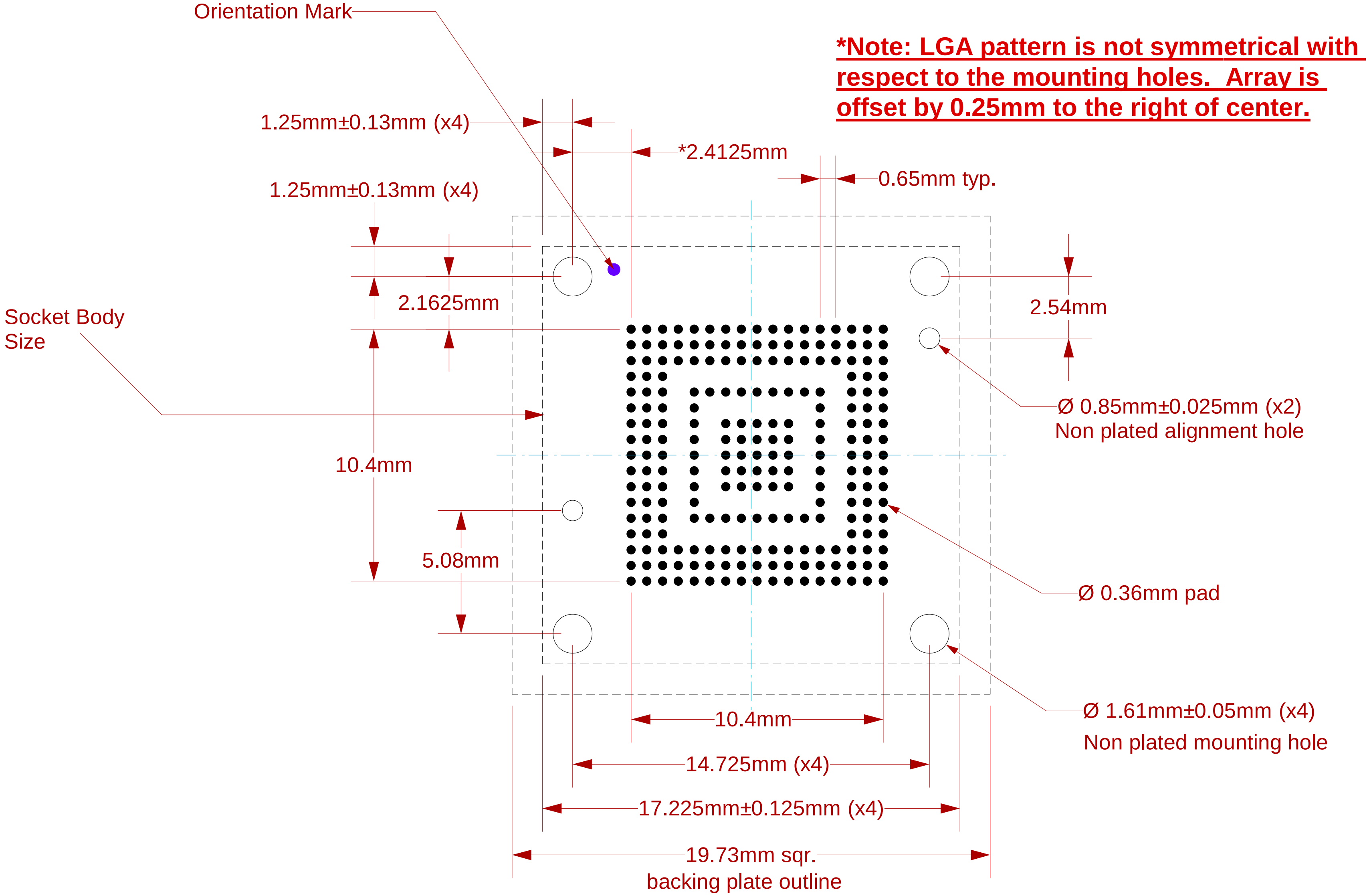
	File: XG-LGA-7001 Dwg	Modified: 8/3/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View



***Note: LGA pattern is not symmetrical with respect to the mounting holes. Array is offset by 0.25mm to the right of center.**

Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

All dimensions are in mm unless stated otherwise

Recommended PCB Layout Tolerances: ±0.025mm [±0.001”] unless stated otherwise.

XG-LGA-7001 Drawing	Status: Released	Scale: 4:1	Rev: B
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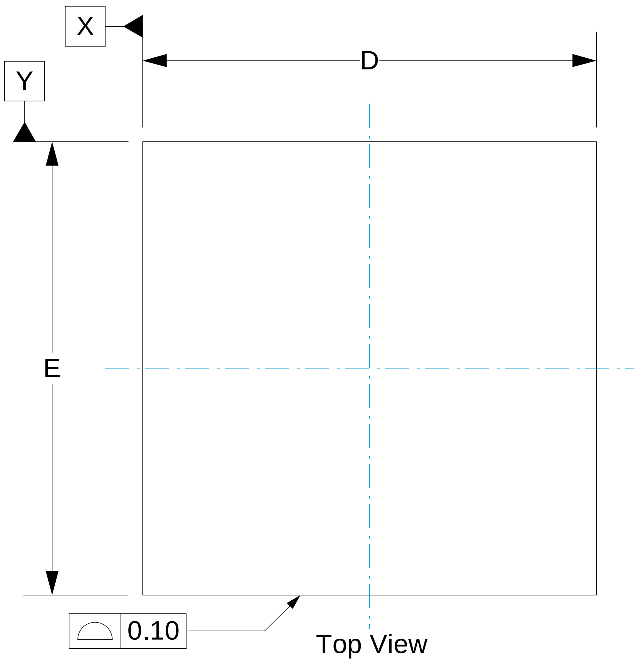
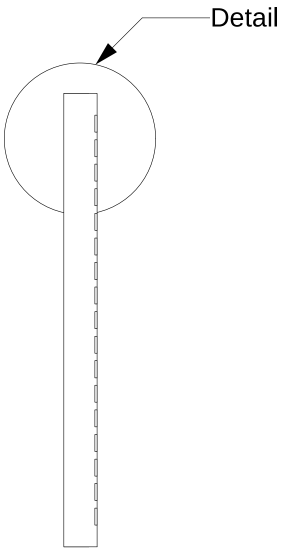
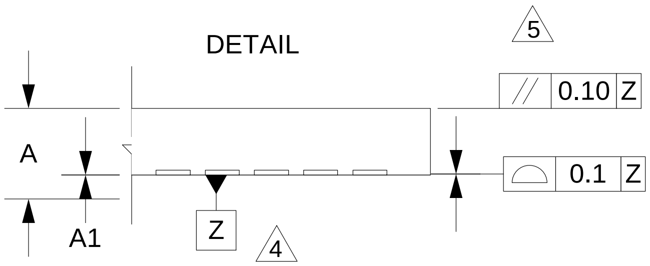
Compatible BGA Spec.

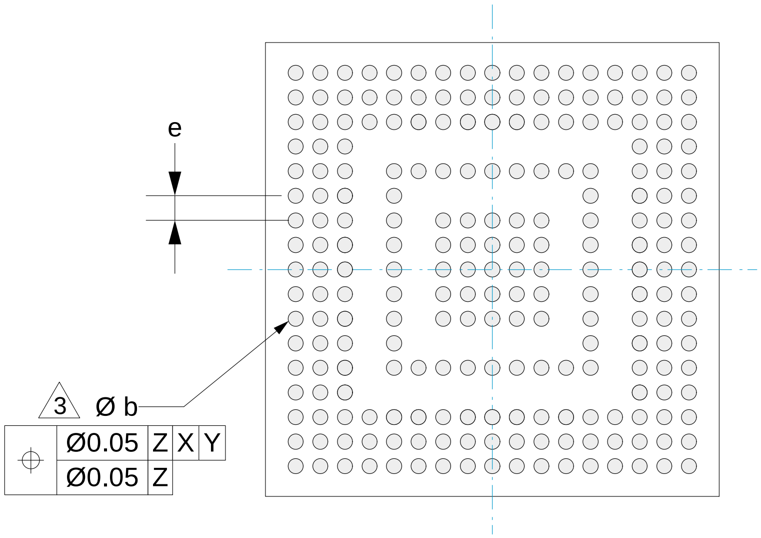


Top View



Side View





Bottom View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum pad diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		0.66
A1	0.0	0
b	0.30	
D	12.0 BSC	
E	12.0 BSC	
e	0.65 BSC	

17 x 17 array

XG-LGA-7001 Drawing

Status: Released

Scale: 5:1

Rev: B

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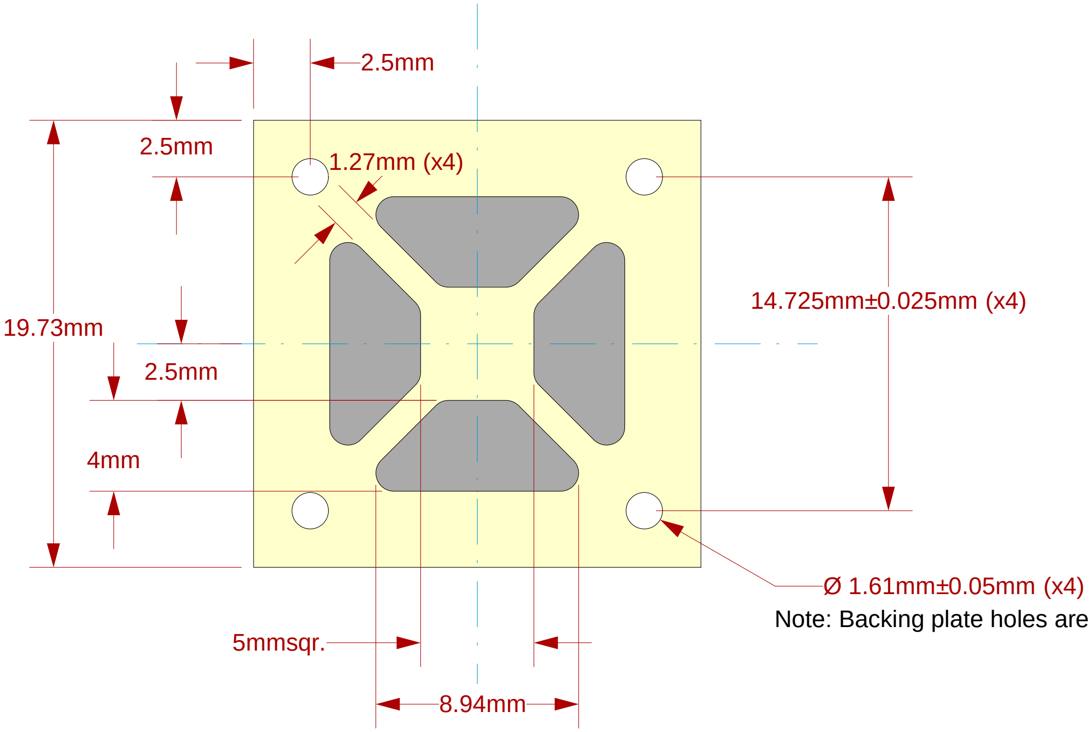
Drawing: J. Glab

Date: 02/12/08

File: XG-LGA-7001 Dwg

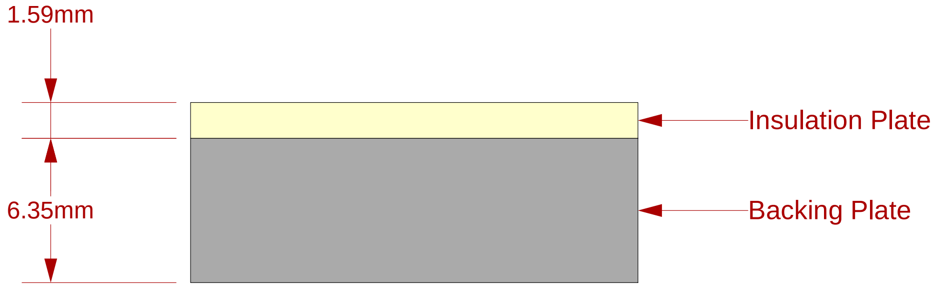
Modified: 8/3/09, AE

Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View



Description: Insulation Plate and Backing Plate

XG-LGA-7001 Drawing	Status: Released	Scale: 3:1	Rev: B
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All dimensions are in mm.
All tolerences are +/- 0.125mm.
(Unless stated otherwise)